

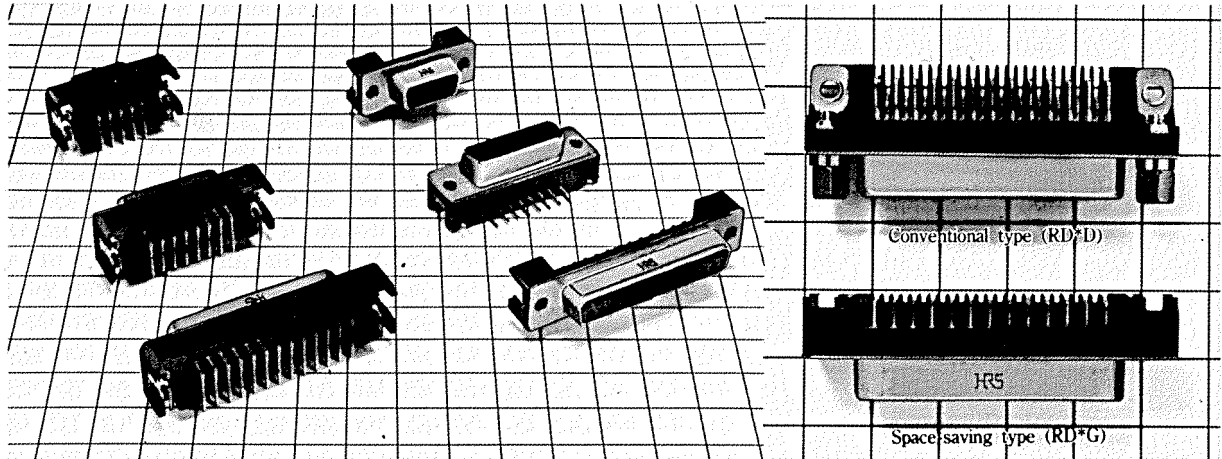
HRS RD*G SERIES SPACE-SAVING D-SUBMINIATURE CONNECTOR

General

The "RD*G" Series Right-angled D-Subminiature connectors are specially developed to answer the needs for smaller and lighter equipment such as personal computers peripherals and workstations.

The PCB mounting section has been reduced in size while the mating section maintains the same configuration as the conventional models.

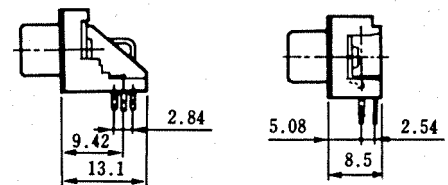
Female 9, 15 and 25 position sizes are available.



Features

- (1) 35% Space-saving is achieved in terms of depth and mounting area as compared to the conventional models (HIROSE's RD*D)
- (2) Weight is approximately 10% less than conventional models.
- (3) Full interchangeability in terms of mating with conventional D-Subminiature connectors. The mating section meets the international standard.
- (4) For smoother insertion and withdrawal, reliable partly gold-plated tulip-shaped contacts are used (same as the conventional models).
- (5) The lock pin grounding system which solders directly to the substrate eliminates troublesome hold down hardware.
- (6) Since they are fixed to the insulator (caulked), the metallic shells and lock pins do not become loose even when the lock screws are removed. This has improved assembly productivity of the units.

Conventional type (RD*D) Space-saving type (RD*G)



- (7) Two lock pin lengths for substrate thickness: t-1.2mm (0.05") and t-1.6mm (0.062") are available.
- (8) There are two Dip post lengths of 3.5mm and 2.8mm.
- (9) The new connectors are suitable for robotic insertion.
- (10) UL94V-0 Insulator material offers excellent heat resistant and chemical resistant capability.
- (11) Metal shell structure offers improved grounding and EMI immunity.

Applications

Electronic equipment such as personal computers, peripherals, workstations, measuring instruments, communications equipment, FA and control devices.

Electrical Performance

Electrical performance	
Current capacity	3A
Voltage rating	350V AC
Insulation resistance	5,000 ohms or more at 500VDC
Contact resistance	25m ohms or less at 100mA DC
Withstanding voltage	One minute at 1,250 VAC r.m.s.

Materials

Materials		
Shell	Copper	Nickel plating
Insulator	PBT resin	Black (UL94V-0)
Contact	Copper alloy	Nickel base with selective gold and solder plating
Lock pin	Copper alloy	Solder plating

Product Numbering System

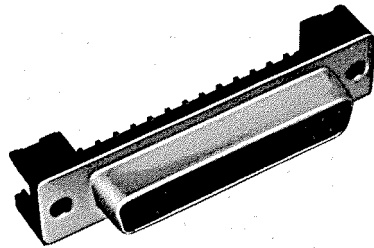
R
D
B
G
1
-
25
S
E
1

(1)
(2)
(3)
(4)
(5)
(6)
(7)
(8)

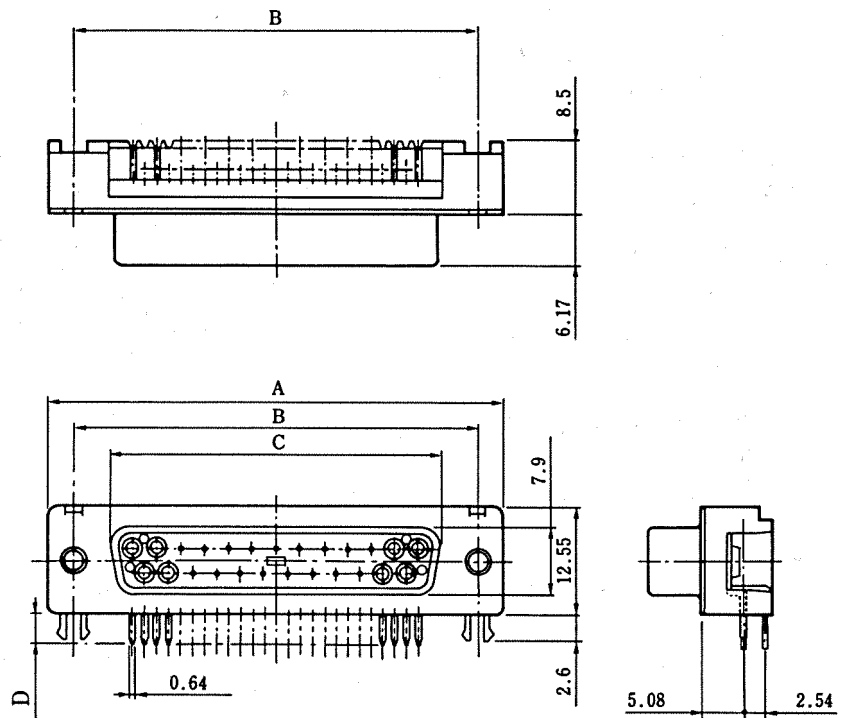
- (1) Series name: D Sub-right angled
- (2) Shell size: E (9), A (15), B (25)
- (3) Model type: G=Space saving type
- (4) Dip post length: Blank=3.5mm (.138")
1=2.8mm (.110")
- (5) No of contacts: 9, 15, 25
- (6) Connector style: S=Female
- (7) Mounting style: E=Grounding lock pin
- (8) Applicable board thickness: 1=(t1.6mm)1.6mm (0.62"), 2=(t1.2mm)1.2mm (0.50")

(Note) Locking screws are available separately.

Female Connector



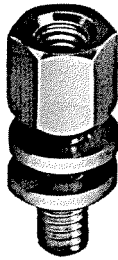
CL211-5206-3
RDBG-25SE1



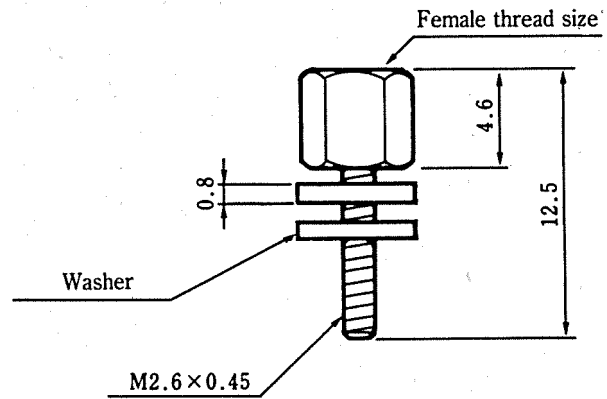
Unit: mm

HRS No.	Part Number	No. of Contacts	A	B	C	D	Applicable substrate thickness
CL211-5200-7	RDEG-9SE1	9	30.81	24.99	16.34	3.5	1.6
CL211-5201-0	RDEG-9SE2						1.2
CL211-5204-8	RDAG-15SE1	15	39.14	33.32	24.66		1.6
CL211-5205-0	RDAG-15SE2						1.2
CL211-5206-3	RDBG-25SE1	25	53.04	47.04	38.38		1.6
CL211-5207-6	RDBG-25SE2						1.2
CL211-5250-5	RDEG1-9SE1	9	30.81	24.99	16.34	2.8	1.6
CL211-5251-8	RDEG1-9SE2						1.2
CL211-5254-6	RDAG1-15SE1	15	39.14	33.32	24.66		1.6
CL211-5255-9	RDAG1-15SE2						1.2
CL211-5256-1	RDBG1-25SE1	25	53.04	47.04	38.38		1.6
CL211-5257-4	RDBG1-25SE2						1.2

Locking Screw



CL211-5182-7-01
RDG-LNA-W2(01)

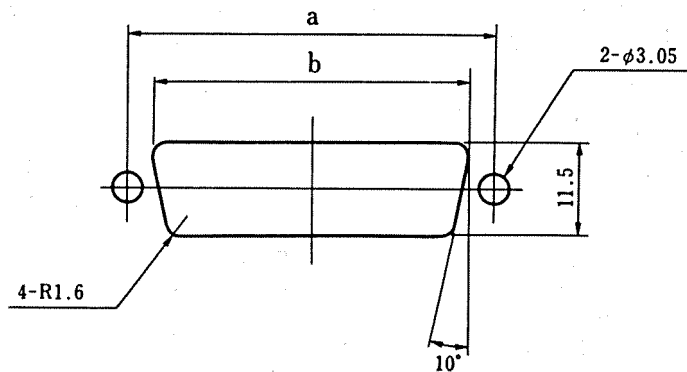


HRS No.	Part Number	Female thread size	No. of washers	Applicable panel thickness	Packaging unit (per bag)
CL211-5180-1-01	RDG-LNA(01)	M2.6X0.45	0	1.6~2.0	100
CL211-5181-4-01	RDG-LNA-W1(01)		1	0.8~1.2	
CL211-5182-7-01	RDG-LNA-W2(01)		2	0~0.4	
CL211-5183-0-01	RDG-LNA(4-40)(01)	No. 4-40UNC	0	1.6~2.0	100
CL211-5184-2-01	RDG-LNA(4-40)-W1(01)		1	0.8~1.2	
CL211-5185-5-01	RDG-LNA(4-40)-W2(01)		2	0~0.4	

*All models are nickel-plated

Panel Mounting Dimensions

For hexagon locking screws

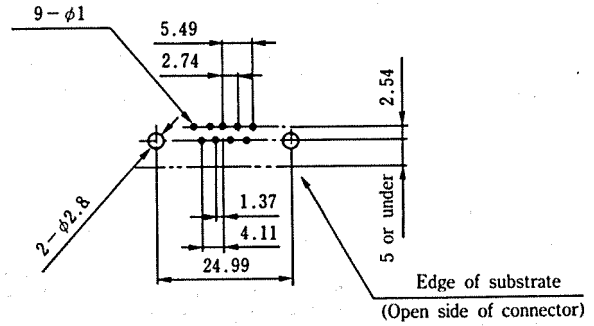


Unit: mm

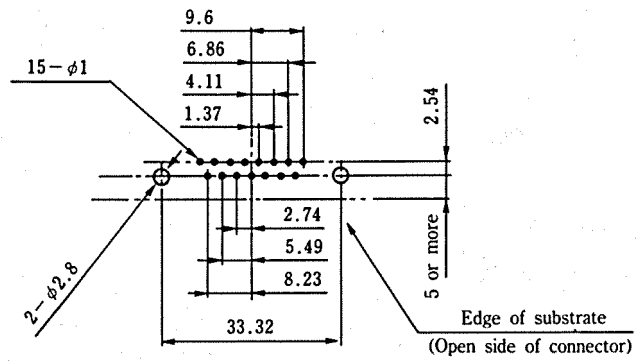
Shell size	a	b
E	24.99	20.2
A	33.32	28.6
B	47.04	42.3

PC Board Layout (mm)

- RDEG-9SE1 (Substrate thickness $t=1.6$)
- RDEG1-9SE1 (Substrate thickness $t=1.6$)
- RDEG-9SE2 (Substrate thickness $t=1.2$)
- RDEG1-9SE2 (Substrate thickness $t=1.2$)



- RDAG-15SE1 (Substrate thickness $t=1.6$)
- RDAG1-15SE1 (Substrate thickness $t=1.6$)
- RDAG-15SE2 (Substrate thickness $t=1.2$)
- RDAG1-15SE2 (Substrate thickness $t=1.2$)



- RDBG-25SE1 (Substrate thickness $t=1.6$)
- RDBG1-25SE1 (Substrate thickness $t=1.6$)
- RDBG-25SE2 (Substrate thickness $t=1.2$)
- RDBG1-25SE2 (Substrate thickness $t=1.2$)

